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(12) **United States Design Patent**
Yoshihira et al.

(10) **Patent No.:** **US D476,962 S**

(45) **Date of Patent:** **** Jul. 8, 2003**

(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/168,143**

(22) Filed: **Sep. 27, 2002**

(30) **Foreign Application Priority Data**

Mar. 29, 2002 (JP) 2002-008487
Mar. 29, 2002 (JP) 2002-008488

(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/110, 123,
D13/125, 179, 182; 174/16.3, 52.1, 52.2,
52.4, 260, 261, 273; 257/676, 690, 691,
724, 787; 361/718, 728, 747, 748, 760,
774, 784, 785, 813, 820

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Assistant Examiner—Selina Sikder

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Maier & Neustadt, P.C.

(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of a semiconductor device, showing our new design;

FIG. 2 is a rear perspective view thereof;

FIG. 3 is a top plan view thereof; a bottom plan view being a mirror image thereof;

FIG. 4 is a right side elevational view thereof; a left side elevational view being a mirror image thereof;

FIG. 5 is a front elevational view thereof;

FIG. 6 is a rear elevational view thereof;

FIG. 7 is a front perspective view of a second embodiment of a semiconductor device, showing our new design;

FIG. 8 is a rear perspective view thereof;

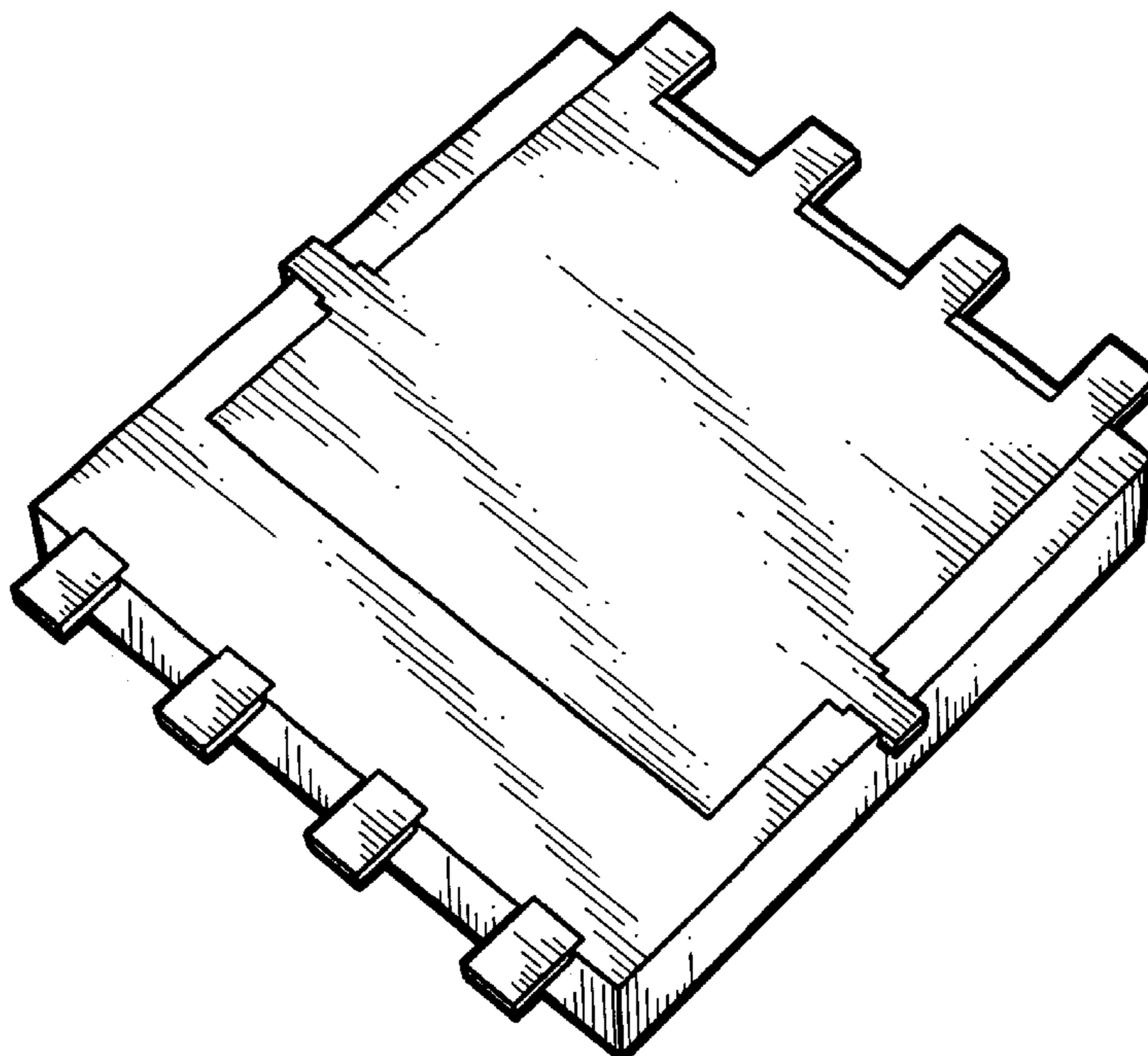
FIG. 9 is a top plan view thereof; a bottom plan view being a mirror image thereof;

FIG. 10 is a right side elevational view thereof; a left side elevational view being a mirror image thereof;

FIG. 11 is a front elevational view thereof; and,

FIG. 12 is a rear elevational view thereof.

1 Claim, 4 Drawing Sheets



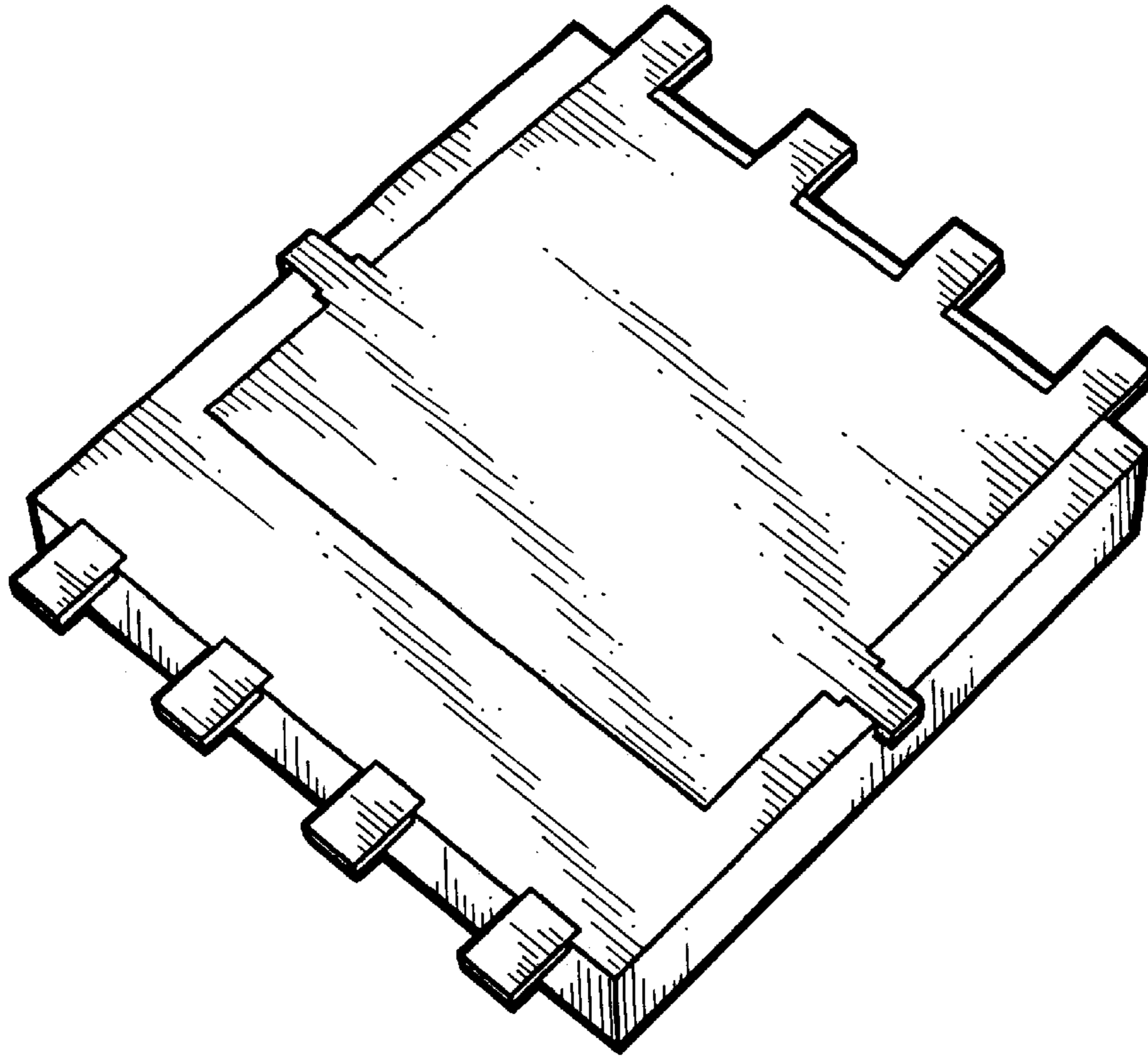


Fig.1

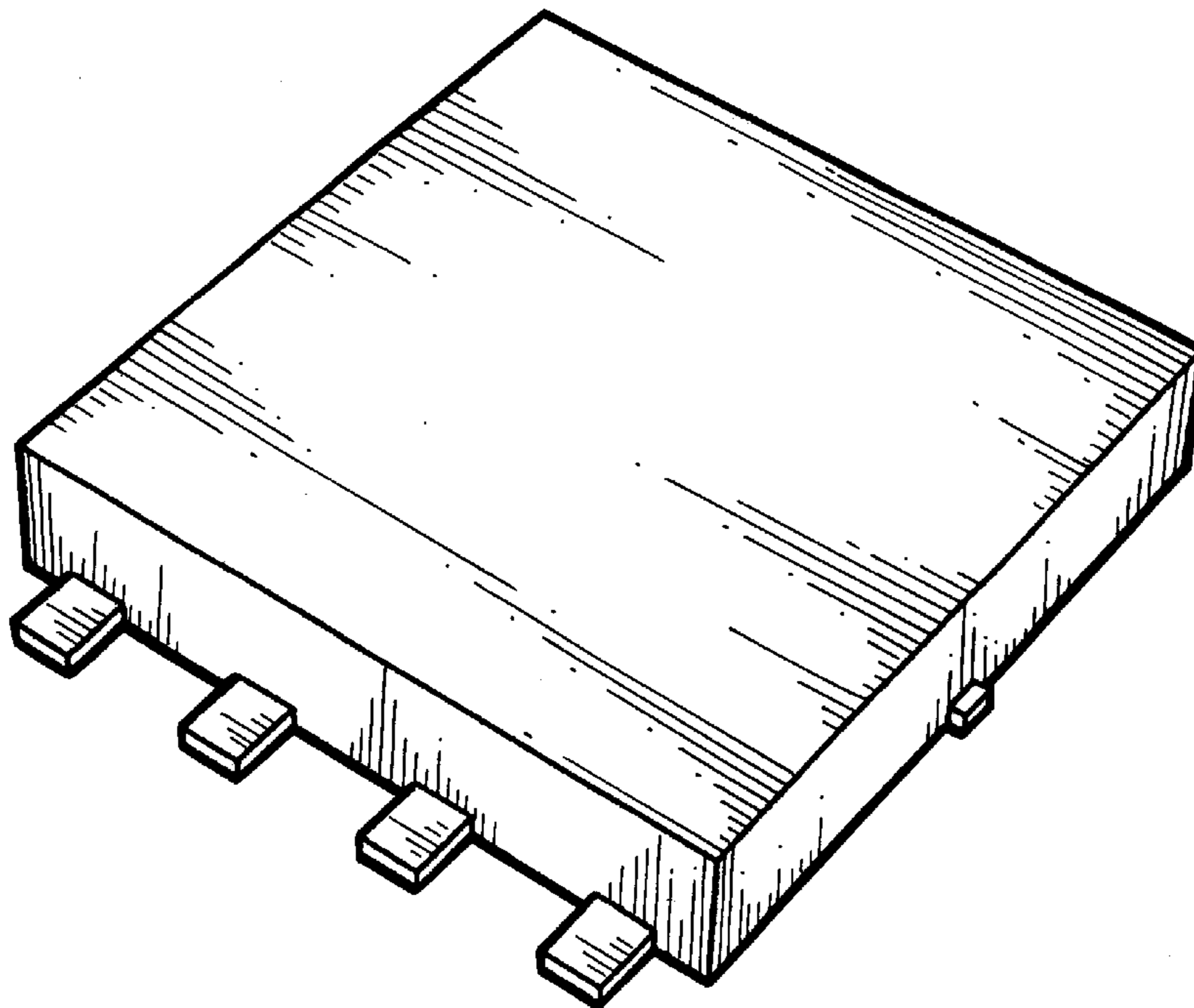


Fig.2

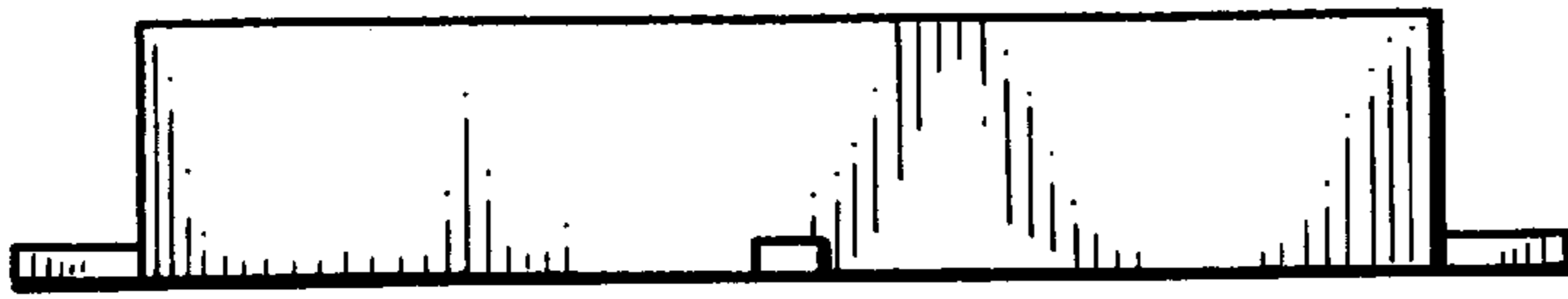


Fig.3

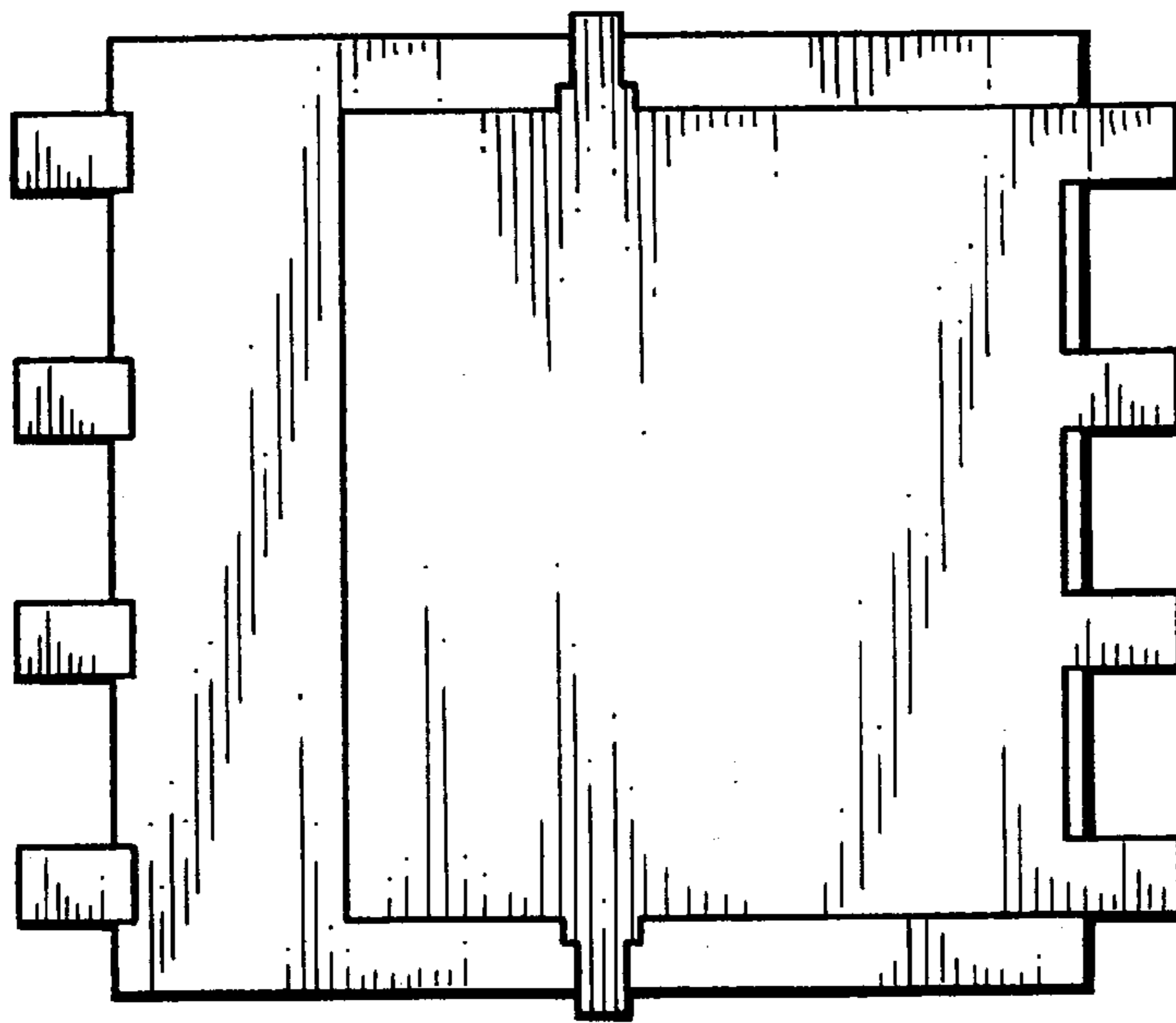


Fig.5



Fig.4

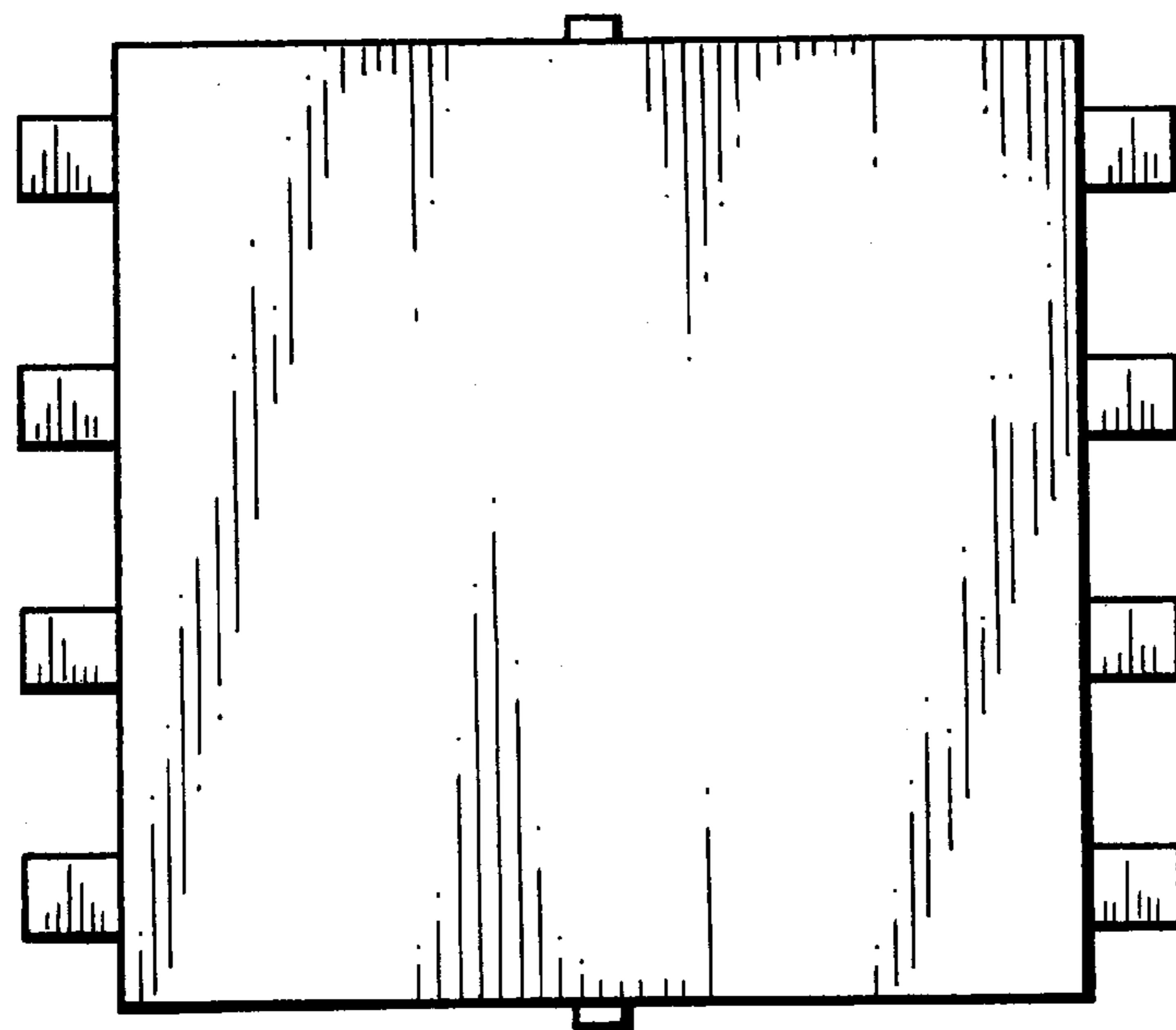


Fig.6

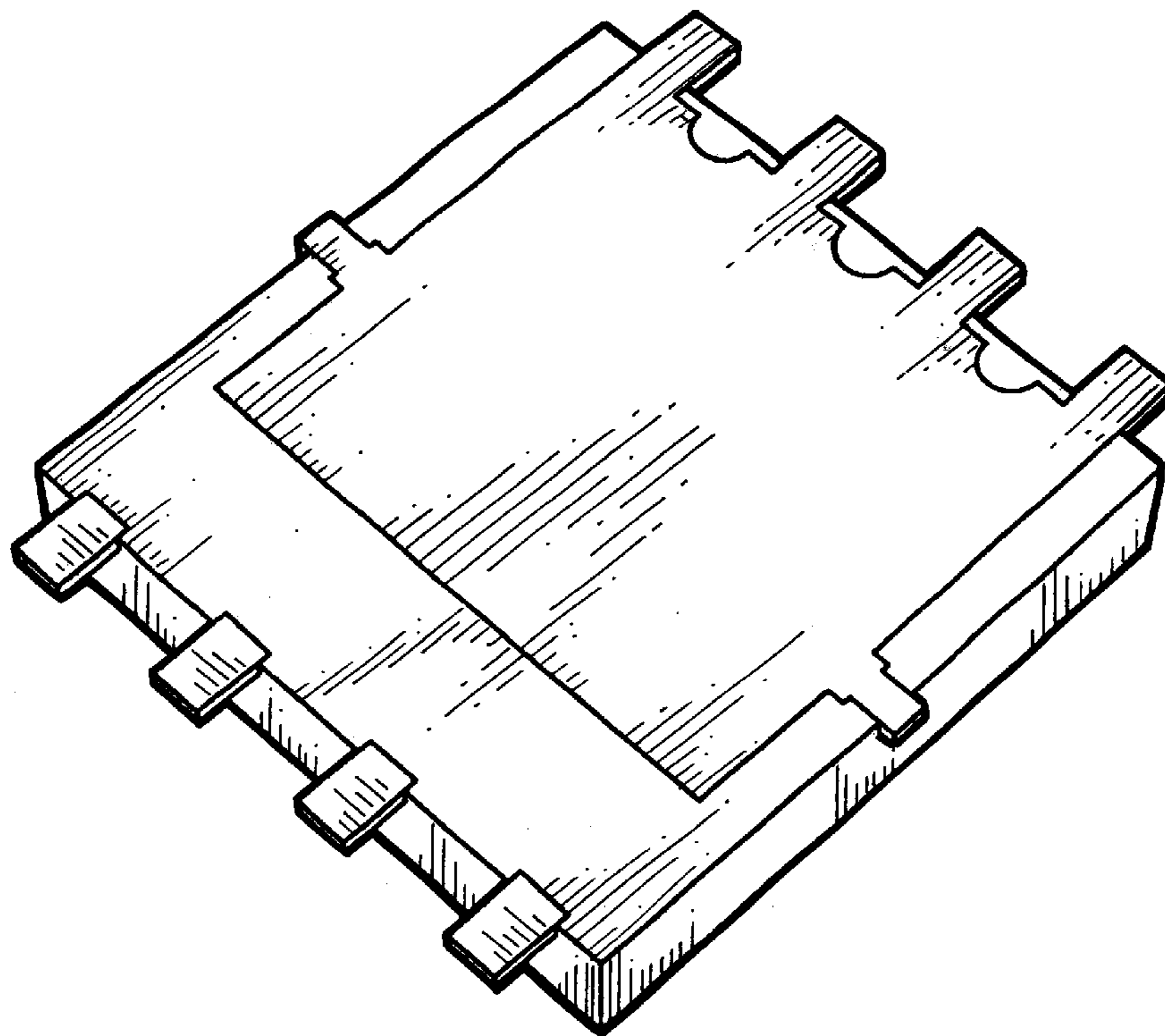


Fig. 7

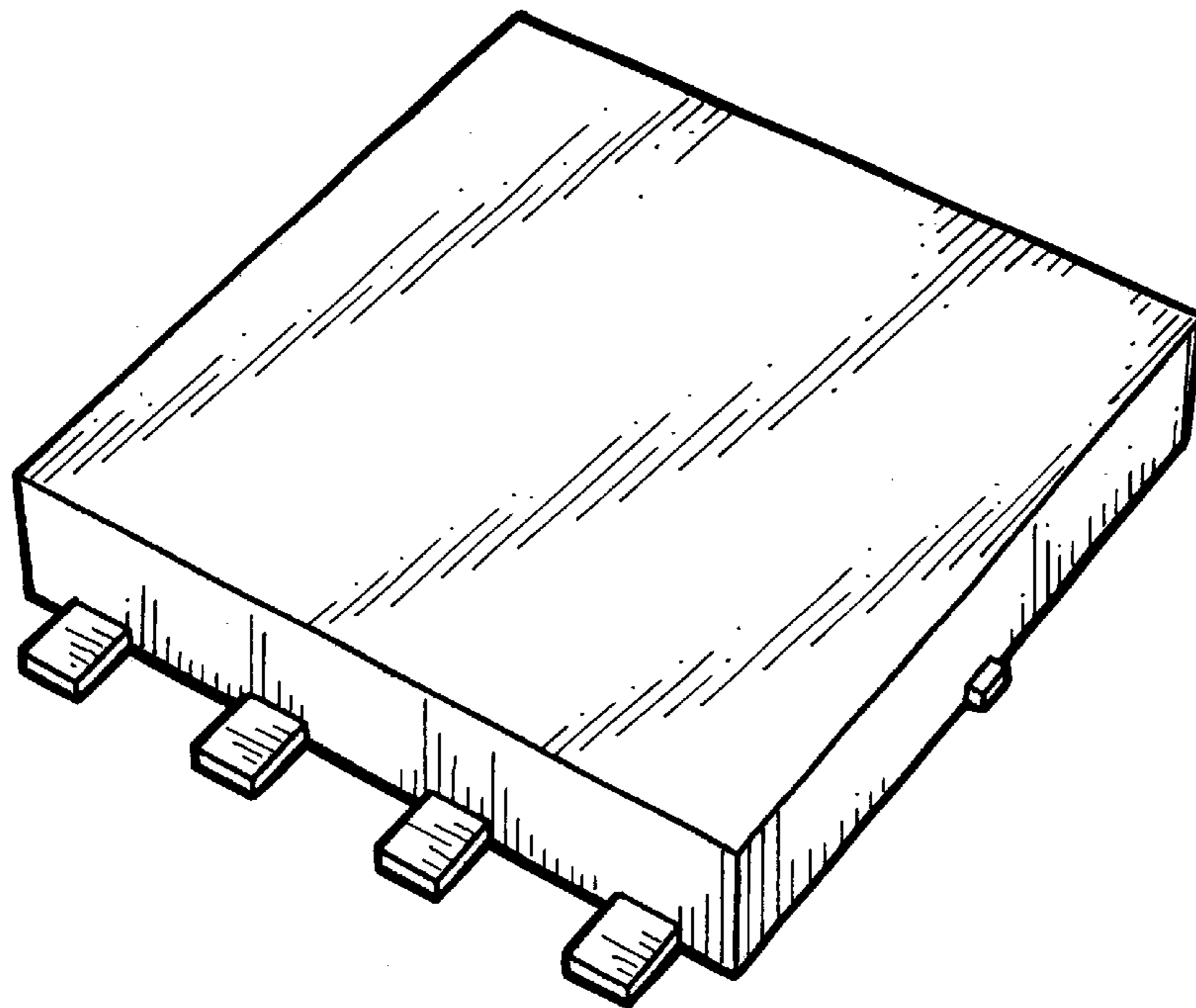


Fig. 8

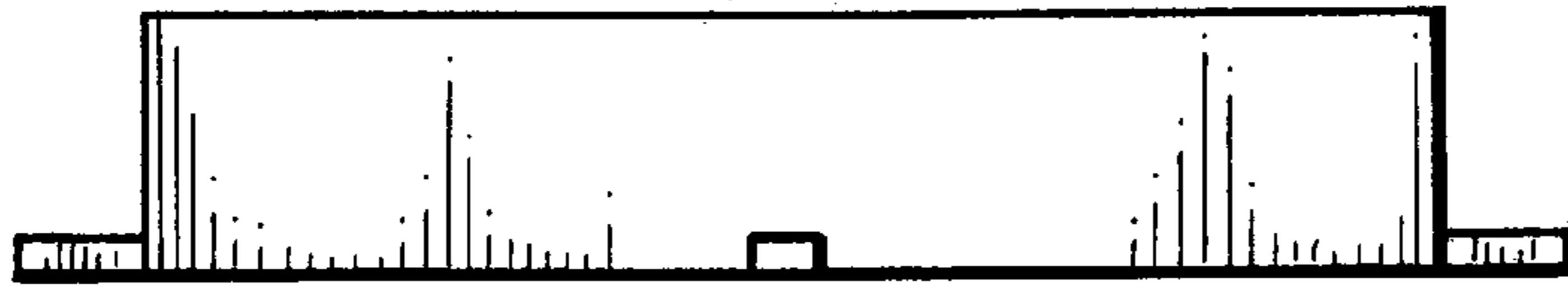


Fig. 9

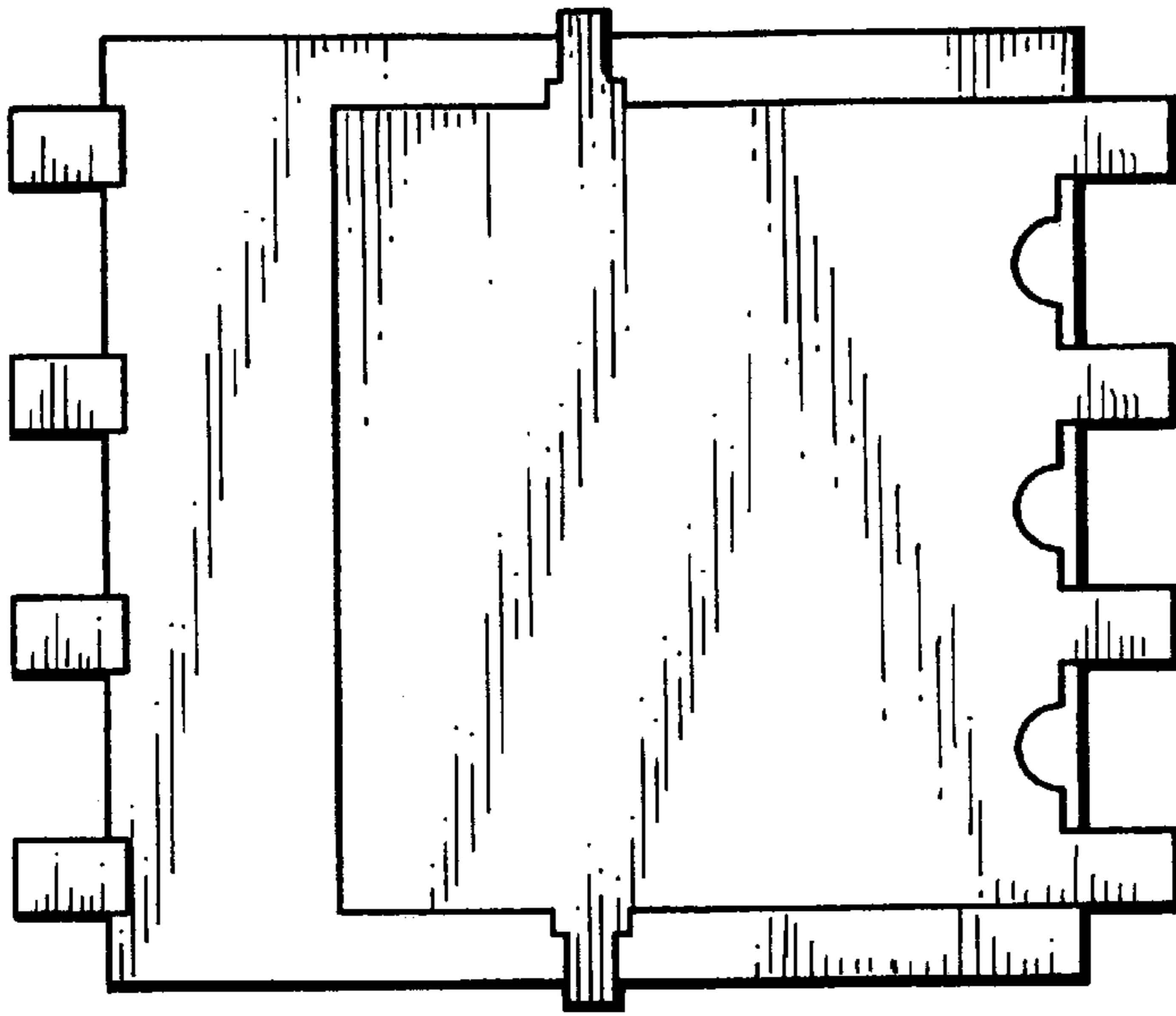


Fig. 11

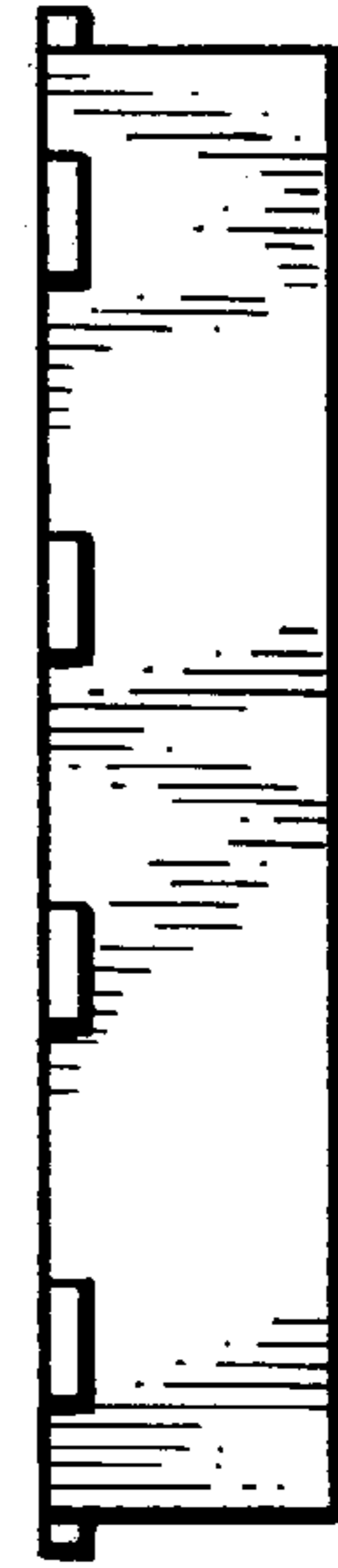


Fig. 10

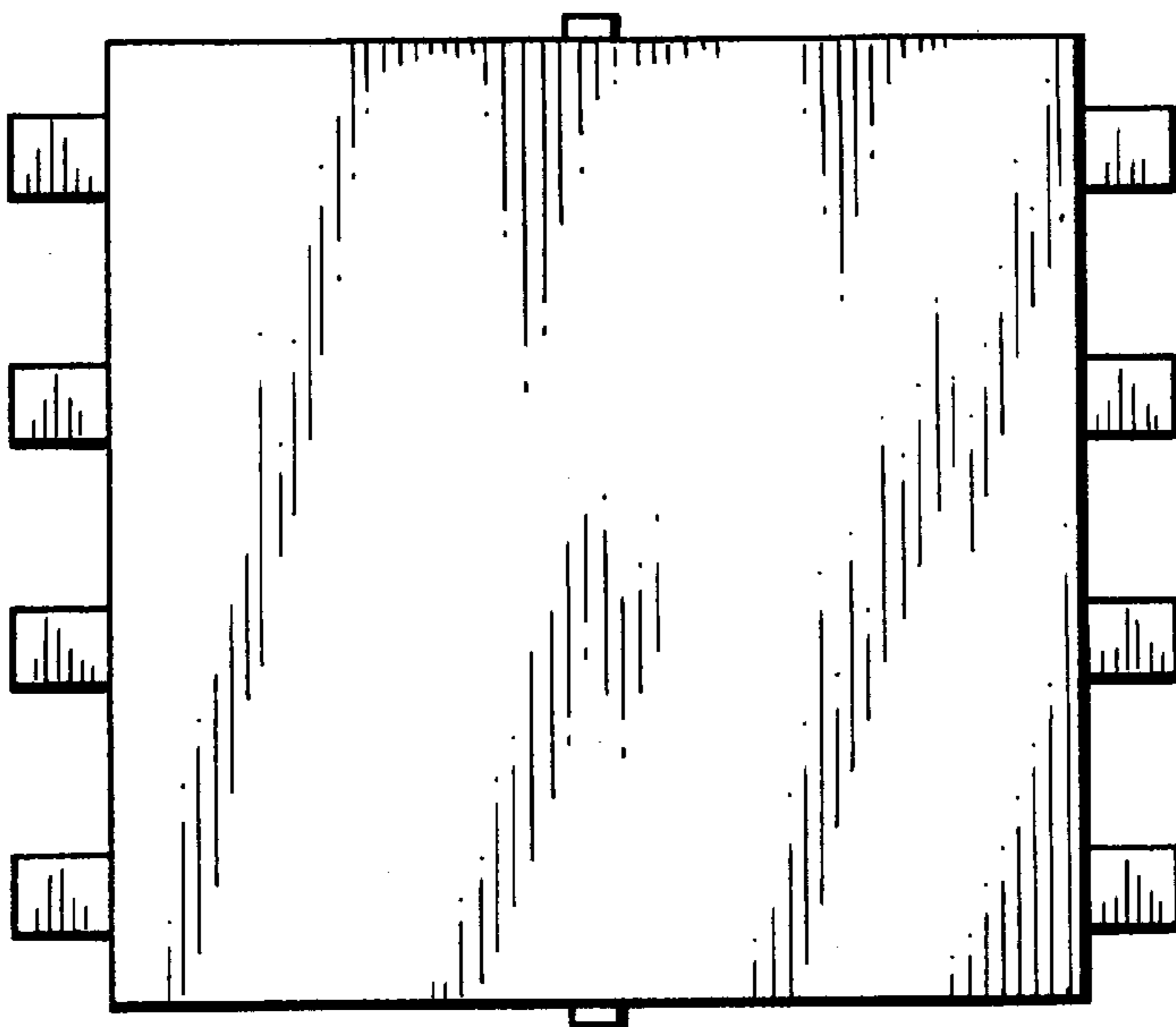


Fig. 12